



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® SO-8</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HR./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
BOND INT	920	440 000	200 °C + N2	0	0
HAST	7375	737 450	130 °C, 85 % RH	0	0
Power Cycle	164	2 460 000	DELTA T <sub>j</sub> = 100 °C	0	0
Pressure Pot	7005	672 480	121°, 15 PSIG	0	0
Solder DUNK	1062	3186	260 °C, 10 s	0	0
Solderability	75	720	883 M2003	0	0
Temp. Cycle	9925	6 865 300	-55 °C to 150 °C	0	0